ON Semiconductor				9/20/2020
Base Part		NVBLS0D5N04M8	HF	
Orderable Part		NVBLS0D5N04M8TXG	Total weight (mg)	811.7391
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	6.35	Silicon (Si)	7440-21-3	100
Die Attach Solder	7.6901	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	95.5
		Tin (Sn)	7440-31-5	2
Lead Frame	474.555	Nickel (Ni)	7440-02-0	0.05
		Iron (Fe)	7439-89-6	0.1
		Copper (Cu)	7440-50-8	99.82
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-Black	314.85	Carbon Black (C)	1333-86-4	0.5
		Fused Silica (SiO2)	60676-86-0	87.5
		Ortho Cresol Novolac Resin	29690-82-2	6
		Phenolic Resin (Novolac)	9003-35-4	6
Plating	8.12	Tin (Sn)	7440-31-5	100
Wire Bond - Al	0.174	Aluminum (Al)	7429-90-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of RoHS restricted substances. Lead (Pb) and lead oxide (PbO) are exempted with the RoHS exemption 7(a), 7(c) and 15. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

https://www.onsemi.com/pub/Collateral/BRD8022-D.PDF